# MSB92ASWT1

**Preferred Device** 

# PNP Silicon General Purpose High Voltage Transistor

This PNP Silicon Planar Transistor is designed for general purpose amplifier applications. This device is housed in the SC-70/SOT-323 package which is designed for low power surface mount applications.

### **Features**

• Pb-Free Package is Available

### **MAXIMUM RATINGS** $(T_A = 25^{\circ}C)$

Rating	Symbol	Value	Unit
Collector-Base Voltage	V <sub>(BR)CBO</sub>	-300	Vdc
Collector-Emitter Voltage	V <sub>(BR)CEO</sub>	-300	Vdc
Emitter-Base Voltage	V <sub>(BR)EBO</sub>	-5.0	Vdc
Collector Current – Continuous	I <sub>C</sub>	500	mAdc
Electrostatic Discharge	ESD	MBM > 16,000, MM > 2,000	V

### THERMAL CHARACTERISTICS

Rating	Symbol	Max	Unit	
Power Dissipation (Note 1)	P <sub>D</sub>	150	mW	
Junction Temperature	TJ	150	°C	
Storage Temperature Range	T <sub>stg</sub>	-55 to +150	°C	

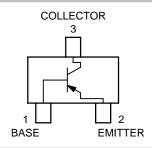
Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

 Device mounted on a FR-4 glass epoxy printed circuit board using the minimum recommended footprint.



# ON Semiconductor®

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SC-70 (SOT-323) CASE 419 STYLE 3

### MARKING DIAGRAM



D3 = Device Code M = Date Code\* • Pb-Free Package

(Note: Microdot may be in either location) \*Date Code orientation may vary depending upon manufacturing location.

### ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>
MSB92ASWT1	SC-70/ SOT-323	3000/Tape & Reel
MSB92ASWT1G	SC-70/ SOT-323 (Pb-Free)	3000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

**Preferred** devices are recommended choices for future use and best overall value.

# MSB92ASWT1

# **ELECTRICAL CHARACTERISTICS**

Characteristic	Symbol	Min	Max	Unit
Collector-Emitter Breakdown Voltage $(I_C = -1.0 \text{ mAdc}, I_B = 0)$	V <sub>(BR)CEO</sub>	-300	_	Vdc
Collector-Base Breakdown Voltage $(I_C = -100 \mu Adc, I_E = 0)$	V <sub>(BR)CBO</sub>	-300	-	Vdc
Emitter-Base Breakdown Voltage ( $I_E = -100 \mu Adc, I_E = 0$ )	V <sub>(BR)EBO</sub>	-5.0	_	Vdc
Collector-Base Cutoff Current $(V_{CB} = 300 \text{ Vdc}, I_E = 0)$	I <sub>CBO</sub>	-	-0.25	μΑ
Emitter–Base Cutoff Current $(V_{EB} = -3.0 \text{ Vdc}, I_{B} = 0)$	I <sub>EBO</sub>	-	-0.1	μΑ
DC Current Gain (Note 2)	h <sub>FE1</sub> h <sub>FE2</sub> h <sub>FE3</sub>	120 40 25	200 - -	-
Collector-Emitter Saturation Voltage (Note 2) $(I_C = -20 \text{ mAdc}, I_B = -2.0 \text{ mAdc})$	V <sub>CE(sat)</sub>	-	-0.5	Vdc
Base–Emitter Saturation Voltage $(I_C = -20 \text{ mAdc}, I_B = -2.0 \text{ mAdc})$	V <sub>BE(sat)</sub>	-	-0.9	Vdc
SMALL SIGNAL CHARACTERISTICS				
Current – Gain – Bandwidth Product (I <sub>C</sub> = –10 mAdc, V <sub>CE</sub> = –20 Vdc, f = 20 MHz)	f⊤	50	_	MHz

 $C_{cb}$ 

pF

6.0

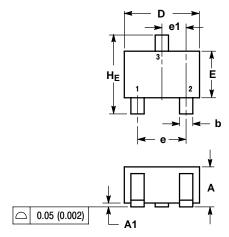
Collector–Base Capacitance (V<sub>CB</sub> = -20 Vdc, I<sub>E</sub> = 0, f = 1.0 MHz)

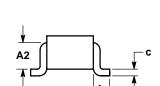
<sup>2.</sup> Pulse Test: Pulse Width  $\leq$  300  $\mu$ s, D.C.  $\leq$  2%.

### MSB92ASWT1

### PACKAGE DIMENSIONS

SC-70 (SOT-323) CASE 419-04 ISSUE M





#### NOTES:

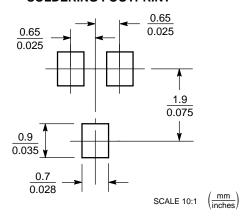
- DIMENSIONING AND TOLERANCING PER ANSI
  A
- 2. CONTROLLING DIMENSION: INCH.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.80	0.90	1.00	0.032	0.035	0.040
A1	0.00	0.05	0.10	0.000	0.002	0.004
A2	0.7 REF			0.028 REF		
b	0.30	0.35	0.40	0.012	0.014	0.016
С	0.10	0.18	0.25	0.004	0.007	0.010
D	1.80	2.10	2.20	0.071	0.083	0.087
E	1.15	1.24	1.35	0.045	0.049	0.053
е	1.20	1.30	1.40	0.047	0.051	0.055
e1	0.65 BSC			0.026 BSC		
L	0.425 REF			0.017 REF		
He	2.00	2 10	2.40	0.079	0.083	0.095

STYLE 3: PIN 1. BASE

2. EMITTER 3. COLLECTOR

### **SOLDERING FOOTPRINT\***



\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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